



**You are cordially invited to the Huntsville EMC Chapter Technical Presentation**

**Thursday, 13 May 2010 at 5:30 p.m.**

**Speaker:**

Mr. John Andresakis, Oak-Mitsui Technologies  
*“Use Of Buried Capacitance Layers In Printed Circuit Boards:  
Performance And Lessons From A Real World Example”*

**Meal Sponsor & Meeting Location:**

Mr. Mike Kirk, Agilent Technologies  
*“Fried Chicken With All The Fixin’s”*  
ADTRAN Inc. 2 East Conference Center Room #273

The Huntsville chapter of the IEEE Electromagnetic Compatibility (EMC) Society invites you to attend the technical presentation by John Andresakis, Vice President of Strategic Technology for Oak-Mitsui Technologies. The meeting will be held on 13 May 2010. The meeting will begin at 5:30 pm and will last approximately two hours. Dinner is being provided by the Mike Kirk of Agilent Technologies, Inc. Dinner will be Fried Chicken with all the Fixin’s.

Embedded capacitor technology has been driven by the need to save board area and/or reduce board size, increase functionality, lower costs and improve electrical performance. This technology has been utilized to enhance signal integrity, reduce impedance at high frequency and dampen noise, and not necessarily just to remove discrete capacitors.

We will show that by using thin core planes and simulation tools one can reduce the number of discrete capacitors and get better electrical performance. The actual number and type (size) of capacitors removed will be presented. In addition to discrete capacitor reduction, the amount of electro-magnetic radiation from the board (which can cause EMI issues) will be shown to be reduced by utilizing the embedded capacitor planes. This is attributed to the reduction in power/ground plane resonance. With a good predictive model, the decision to utilize embedded capacitors is simplified.

The meeting will be held at ADTRAN in the East Tower Lobby Conference Room. The directions are included on page 2 (follow the **BLUE** line on the map).

The meeting is open to anyone interested in EMC: IEEE membership is not required to attend.

**Please RSVP to Paul Stover ([paul.stover@adtran.com](mailto:paul.stover@adtran.com)) as soon as you can, but no later than close of business 11 May 2010 with your intent to attend.**

I hope to see you there!

Jack McFadden, NCE/NCT  
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IEEE EMC Society  
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Huntsville EMCS website: <http://www.HuntsvilleEMC.org>

IEEE EMCS website: <http://www.ewh.ieee.org/soc/emcs/>

Do not park in the visitor parking lot or try to use the main entrance to the East Tower. You must following the blue line on this map and go around to the back entrance of the East Tower which takes you straight into the Conference Center.

